

HVU133

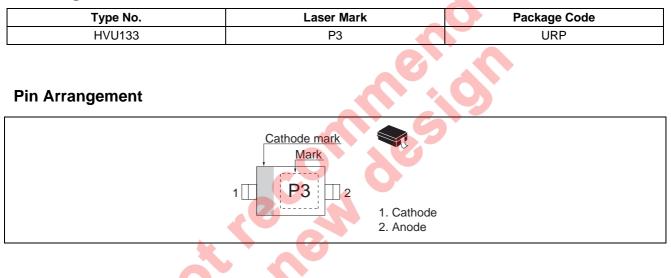
Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0436-0300 (Previous: ADE-208-377B) Rev.3.00 Oct 29, 2004

Features

- Low capacitance. (C1 = 1.0 pF max)
- Low forward resistance. (rf = 0.7Ω max)
- <u>Ultra small Resin Package (URP) is suitable for surface mount design.</u>

Ordering Information





Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	30	V
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

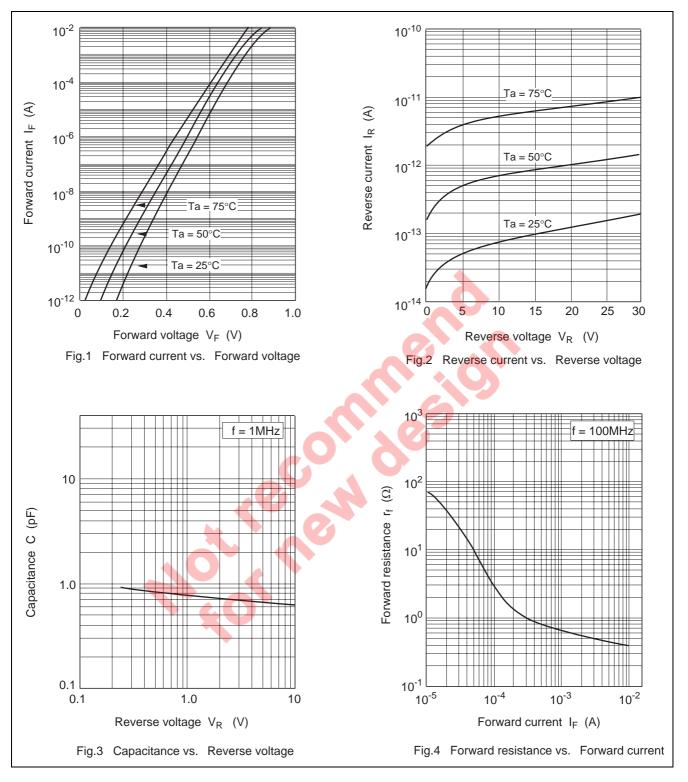
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V _R	30	—	—	V	$I_R = 1\mu A$
Reverse current	I _R	—	—	100	nA	V _R = 25 V
Forward voltage	VF	—	—	0.85	V	$J_F = 2 \text{ mA}$
Capacitance	C ₁	—	—	1.00	pF	V _R = 1 V, f = 1 MHz
	C ₆	—	—	0.90		$V_R = 6 V, f = 1 MHz$
Forward resistance	r _f	—	0.55	0.70	Ω	I _F = 2 mA, f = 100 MHz

 $v_R = 6$

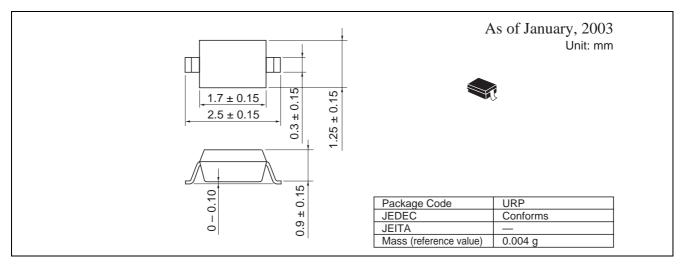


Main Characteristic





Package Dimensions





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